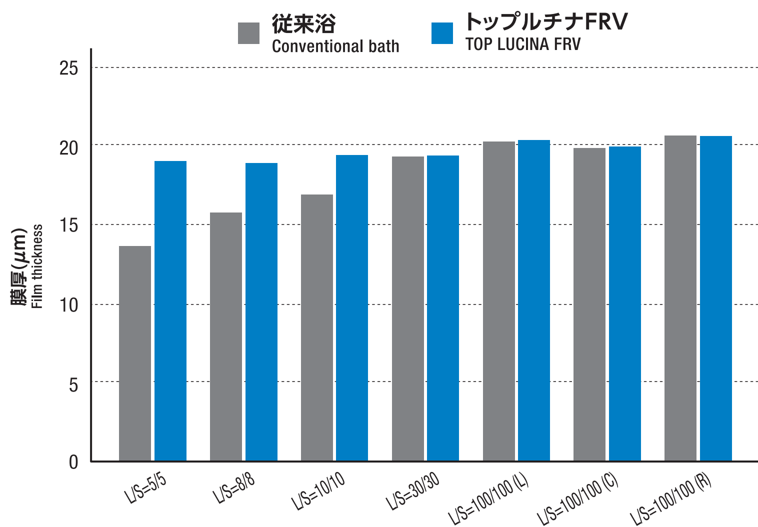
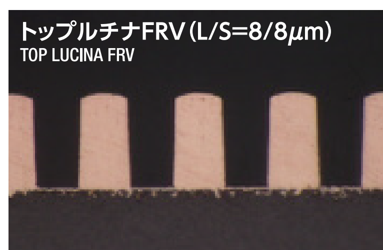
ファインパターン対応ビアフィリング用硫酸銅めっき添加剤
Additives for Acid Copper Plating to Via-filling (For Fine Pattern)

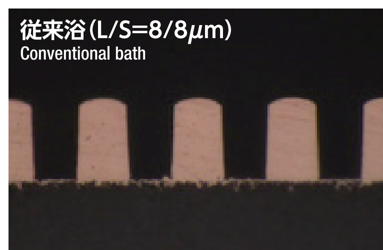
トップルチナFRV
TOP LUCINA FRV

- **微細配線の膜厚低下が少なく膜厚均一性に優れる**
  Reduce thickness variation of micro-patterns, excellent in thickness uniformity
- **配線の断面形状の矩形性が良好**
  Can obtain fine square shapes
- **ブラインドビアホールのフィリングが可能**
  Blind via holes can be filled
- **緻密で平滑な光沢外観が得られ、高展延性の皮膜が得られる**
  Fine and smooth films can be obtained, films with high ductility comes available

優れた膜厚均一性・・・微細配線の膜厚低下が少ない
Excellent in thickness uniformity　Reduce thickness variation of micro-patterns

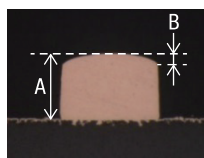



トップルチナFRV(L/S=8/8μm)
TOP LUCINA FRV


従来浴(L/S=8/8μm)
Conventional bath

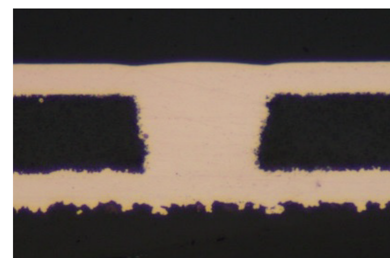
良好な矩形性
Square-shape patterns can be obtained

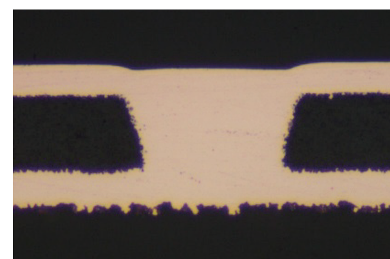
	トップルチナFRV TOP LUCINA FRV	従来浴 Conventional bath
L=30μm 断面形状 Cross-sectional image		
矩形性率 Square-shape ratio	9.8%	16.9%
L=8μm 断面形状 Cross-sectional image		
矩形性率 Square-shape ratio	4.9%	6.8%



矩形性率（%）＝ B(μm)÷ A(μm)
Square-shape ratio

良好なフィリング性
Great via-filling performance


ビア径 60μm　ビア深さ 30μm
Via diameter　Via depth


ビア径 70μm　ビア深さ 30μm
Via diameter　Via depth